This document provides information about the cleaning compatibility between some Interflux soldering products and Kolb cleaners.

### Cleaning Compatibility

<table>
<thead>
<tr>
<th>Soldering Flux</th>
<th>Cleaner</th>
<th>Kolb MultiEx BC 1:2</th>
<th>Kolb MultiEx A12</th>
<th>Kolb MultiEx B 11 1:2,5</th>
</tr>
</thead>
<tbody>
<tr>
<td>IF2005M</td>
<td>+</td>
<td>+</td>
<td>+</td>
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<tr>
<td>IF2005C</td>
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<td>+</td>
<td>+</td>
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<tr>
<td>P2009M</td>
<td>+</td>
<td>++</td>
<td>+</td>
<td></td>
</tr>
<tr>
<td>P2009MLF</td>
<td>++</td>
<td>+</td>
<td>++</td>
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</tr>
<tr>
<td>AF4818PbF</td>
<td>--</td>
<td>+</td>
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</table>

<table>
<thead>
<tr>
<th>Solder Paste</th>
<th>Cleaner</th>
<th>Kolb MultiEx VR</th>
<th>Kolb MultiEx 3DE14 HPA</th>
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</thead>
<tbody>
<tr>
<td>DP5505</td>
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<td>+</td>
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</tr>
<tr>
<td>LP5707</td>
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<td>++</td>
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<td>DP5600</td>
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</table>

<table>
<thead>
<tr>
<th>Solder Wire</th>
<th>Cleaner</th>
<th>Kolb MultiEx VR</th>
<th>Kolb MultiEx 3DE14 HPA</th>
<th>Kolb MultiEx B 11 1:2,5</th>
<th>Kolb MultiEx VR-SP</th>
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</thead>
<tbody>
<tr>
<td>IF14-16</td>
<td>++</td>
<td>++</td>
<td>-</td>
<td>-</td>
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<tr>
<td>Flexsol 903 3,5%</td>
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<td>++</td>
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<td>+</td>
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</tr>
</tbody>
</table>

**NOTE**

The composition and structure of residues after a soldering process may differ from case to case. The influencing parameters can be:

- Residues from the solder mask
- Residues from components
- Residues from other soldering chemistry on the board
- Residues from carriers
- Residues from machine pollution
- Temperature profile of the soldering process
- Amount of used soldering chemistry (due to e.g. thermally heavy boards)
- ...

To get optimal cleaning results, it is possible that cleaning parameters will have to be adapted.

**Cleaning parameters**

- Temperature: 45°C
- Time: 45min